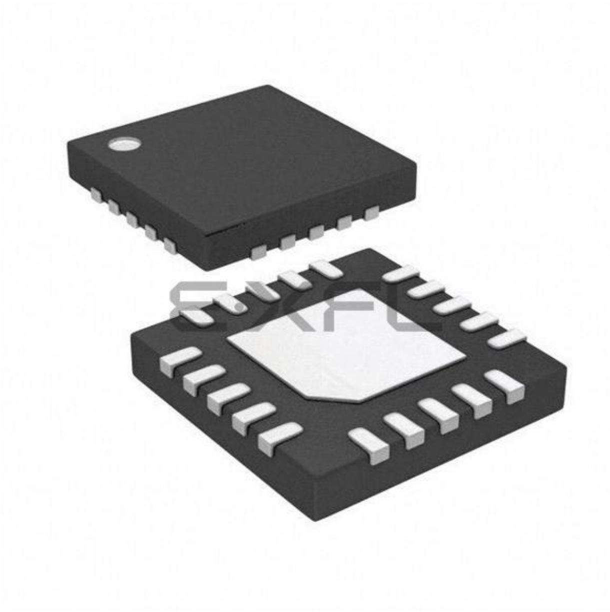
Microchip Technology - PIC16F1508-I/GZ Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1508-i-gz

TABLE 1-2: PIC16(L)F1508/9 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/C1IN+/DAC1OUT1/ICSPDAT/ICDDAT	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	ADC Channel input.
	C1IN+	AN	—	Comparator positive input.
	DAC1OUT1	—	AN	Digital-to-Analog Converter output.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ICDDAT	ST	CMOS	In-Circuit Debug data.
RA1/AN1/CLC4IN1/VREF+/C1IN0-/C2IN0-/ICSPCLK/ICDCLK	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	ADC Channel input.
	CLC4IN1	ST	—	Configurable Logic Cell source input.
	VREF+	AN	—	ADC Positive Voltage Reference input.
	C1IN0-	AN	—	Comparator negative input.
	C2IN0-	AN	—	Comparator negative input.
	ICSPCLK	ST	—	ICSP Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
RA2/AN2/C1OUT/DAC1OUT2/T0CKI/INT/PWM3/CLC1/$\overline{\text{CWG1FLT}}$	RA2	ST	CMOS	General purpose I/O.
	AN2	AN	—	ADC Channel input.
	C1OUT	—	CMOS	Comparator output.
	DAC1OUT2	—	AN	Digital-to-Analog Converter output.
	T0CKI	ST	—	Timer0 clock input.
	INT	ST	—	External interrupt.
	PWM3	—	CMOS	PWM output.
	CLC1	—	CMOS	Configurable Logic Cell source output.
	$\overline{\text{CWG1FLT}}$	ST	—	Complementary Waveform Generator Fault input.
RA3/CLC1IN0/VPP/T1G(1)/$\overline{\text{SS}}$(1)/$\overline{\text{MCLR}}$	RA3	TTL	—	General purpose input with IOC and WPU.
	CLC1IN0	ST	—	Configurable Logic Cell source input.
	VPP	HV	—	Programming voltage.
	T1G	ST	—	Timer1 Gate input.
	$\overline{\text{SS}}$	ST	—	Slave Select input.
	$\overline{\text{MCLR}}$	ST	—	Master Clear with internal pull-up.
RA4/AN3/SOSCO/CLKOUT/T1G	RA4	TTL	CMOS	General purpose I/O.
	AN3	AN	—	ADC Channel input.
	SOSCO	XTAL	XTAL	Secondary Oscillator Connection.
	CLKOUT	—	CMOS	FOSC/4 output.
	T1G	ST	—	Timer1 Gate input.
RA5/CLKIN/T1CKI/NCO1CLK/SOSCI	RA5	TTL	CMOS	General purpose I/O.
	CLKIN	CMOS	—	External clock input (EC mode).
	T1CKI	ST	—	Timer1 clock input.
	NCO1CLK	ST	—	Numerically Controlled Oscillator Clock source input.
	SOSCI	XTAL	XTAL	Secondary Oscillator Connection.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Alternate pin function selected with the APFCON (Register 11-1) register.

5.2.2.4 Peripheral Clock Sources

The clock sources described in this chapter and the Timer's are available to different peripherals. Table 5-1 lists the clocks and timers available for each peripheral.

TABLE 5-1: PERIPHERAL CLOCK SOURCES

	FOSC	FRC	HFINTOSC	LFINTOSC	TMR0	TMR1	TMR2	SOSC
ADC	●	●						
CLC	●	●	●	●	●	●	●	●
COMP						●		●
CWG	●		●					
EUSART	●						●	
MSSP	●						●	
NCO	●		●					
PWM	●						●	
PWRT				●				
TMR0	●							
TMR1	●			●				●
TMR2	●							
WDT				●				

5.2.2.5 Internal Oscillator Frequency Selection

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register.

The postscaled output of the 16 MHz HFINTOSC and 31 kHz LFINTOSC connect to a multiplexer (see Figure 5-1). The Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register (Register 5-1) select the frequency output of the internal oscillators.

Note: Following any Reset, the IRCF<3:0> bits of the OSCCON register are set to '`0111`' and the frequency selection is set to 500 kHz. The user can modify the IRCF bits to select a different frequency.

The IRCF<3:0> bits of the OSCCON register allow duplicate selections for some frequencies. These duplicate choices can offer system design trade-offs. Lower power consumption can be obtained when changing oscillator sources for a given frequency. Faster transition times can be obtained between frequency changes that use the same oscillator source.

5.2.2.6 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 5-7). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 5-7 for more details.

If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 5-3.

Start-up delay specifications are located in Table 29-8, "Oscillator Parameters".

REGISTER 5-2: OSCSTAT: OSCILLATOR STATUS REGISTER

R-1/q	U-0	R-q/q	R-0/q	U-0	U-0	R-0/q	R-0/q
SOSCR	—	OSTS	HFIOFR	—	—	LFIOFR	HFIOFS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Conditional

bit 7 **SOSCR:** Secondary Oscillator Ready bit
If T1OSCEN = `1`:
`1` = Secondary oscillator is ready
`0` = Secondary oscillator is not ready
If T1OSCEN = `0`:
`1` = Timer1 clock source is always ready

bit 6 **Unimplemented:** Read as ‘`0`’

bit 5 **OSTS:** Oscillator Start-up Timer Status bit
When the FOSC<2:0> bits select HS, XT or LP oscillator:
`1` = OST has counted 1024 clocks, device is clocked by the FOSC<2:0> bit selection
`0` = OST is counting, device is clocked from the internal oscillator (INTOSC) selected by the IRCF<3:0> bits.
For all other FOSC<2:0> bit selections:
See Table 5-2, “OSTS Bit Definition”.

bit 4 **HFIOFR:** High-Frequency Internal Oscillator Ready bit
`1` = HFINTOSC is ready
`0` = HFINTOSC is not ready

bit 3-2 **Unimplemented:** Read as ‘`0`’

bit 1 **LFIOFR:** Low-Frequency Internal Oscillator Ready bit
`1` = LFINTOSC is ready
`0` = LFINTOSC is not ready

bit 0 **HFIOFS:** High-Frequency Internal Oscillator Stable bit
`1` = HFINTOSC 16 MHz Oscillator is stable and is driving the INTOSC
`0` = HFINTOSC 16 MHz is not stable, the Start-up Oscillator is driving INTOSC

TABLE 6-5: SUMMARY OF REGISTERS ASSOCIATED WITH RESETS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BORCON	SBOREN	BORFS	—	—	—	—	—	BORRDY	64
PCON	STKOVF	STKUNF	—	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	68
STATUS	—	—	—	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	19
WDTCON	—	—	WDTPS<4:0>					SWDTEN	88

Legend: — = unimplemented bit, reads as ‘0’. Shaded cells are not used by Resets.

TABLE 6-6: SUMMARY OF CONFIGURATION WORD WITH RESETS

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	43
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>			
CONFIG2	13:8	—	—	LVP	—	$\overline{\text{LPBOR}}$	BORV	STVREN	—	43
	7:0	—	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as ‘0’. Shaded cells are not used by Resets.

7.0 INTERRUPTS

The interrupt feature allows certain events to preempt normal program flow. Firmware is used to determine the source of the interrupt and act accordingly. Some interrupts can be configured to wake the MCU from Sleep mode.

This chapter contains the following information for Interrupts:

- Operation
- Interrupt Latency
- Interrupts During Sleep
- INT Pin
- Automatic Context Saving

Many peripherals produce interrupts. Refer to the corresponding chapters for details.

A block diagram of the interrupt logic is shown in Figure 7-1.

FIGURE 7-1: INTERRUPT LOGIC

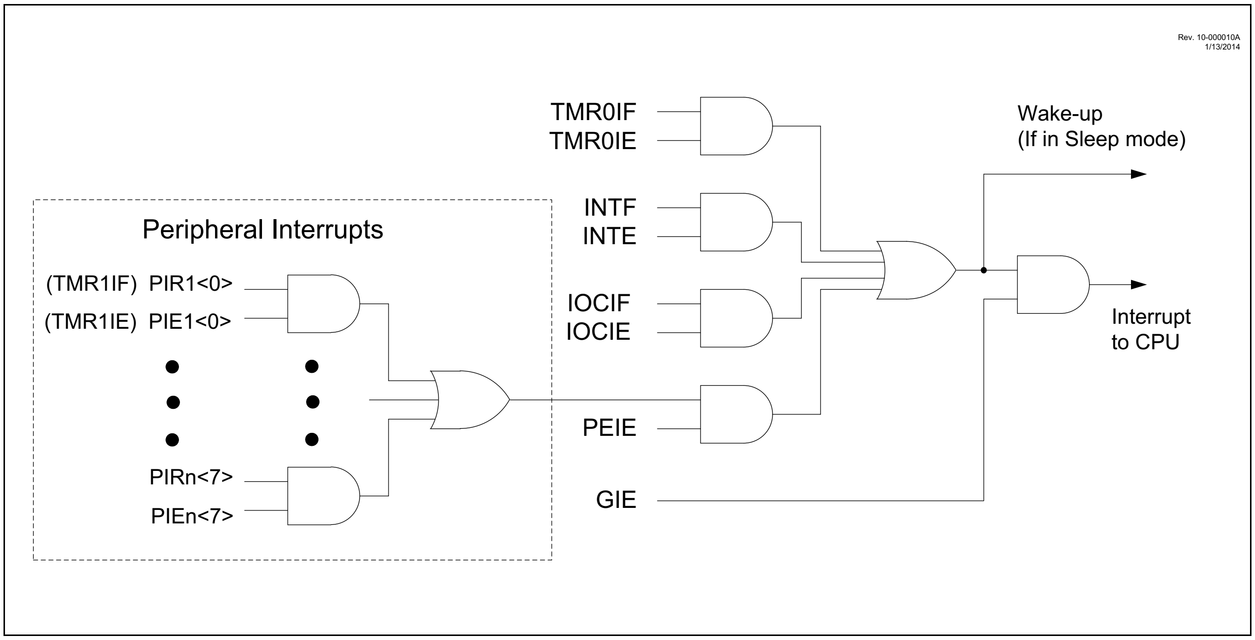
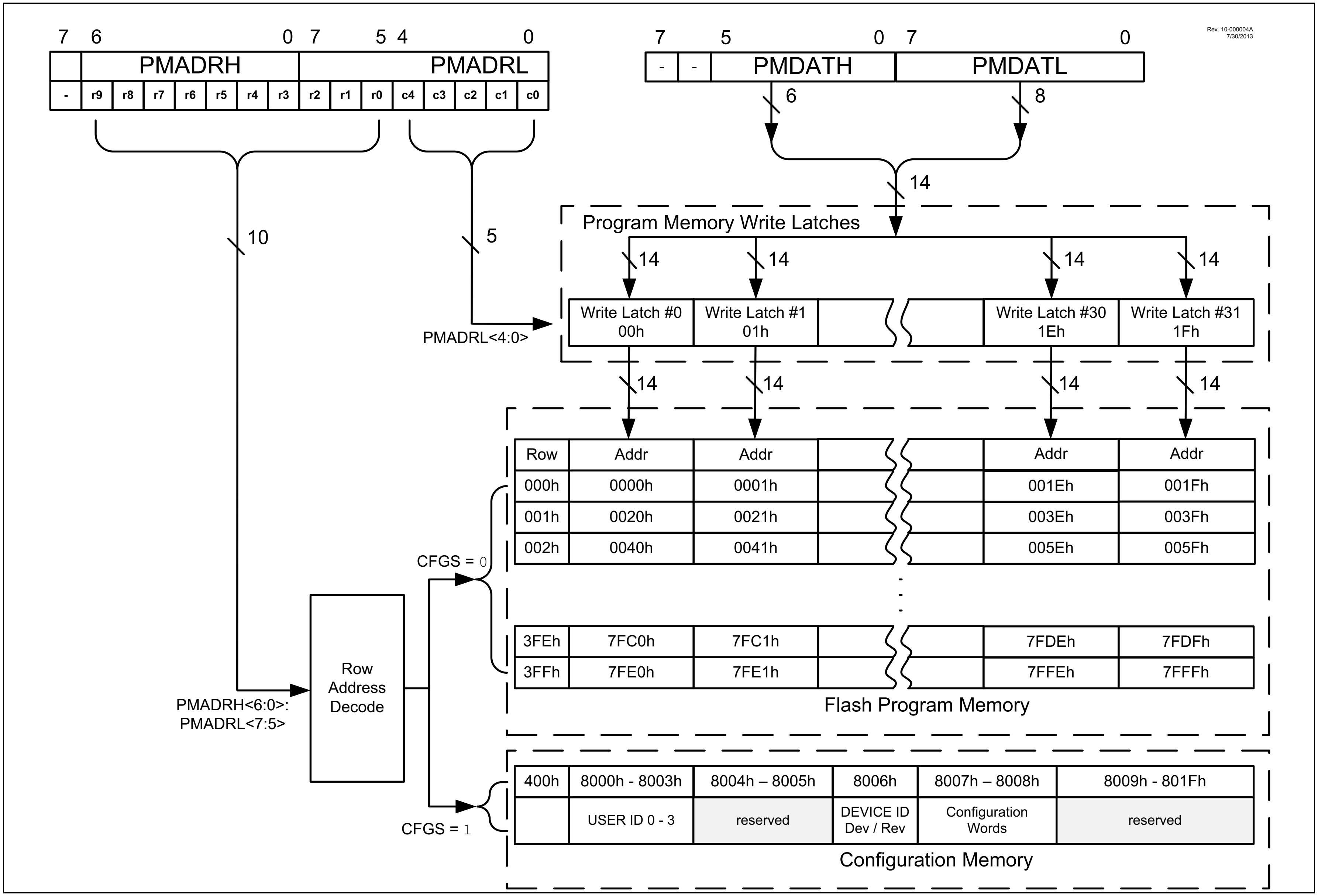


TABLE 7-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	75
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			154
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	—	TMR2IE	TMR1IE	76
PIE2	OSFIE	C2IE	C1IE	—	BCL1IE	NCO1IE	—	—	77
PIE3	—	—	—	—	CLC4IE	CLC3IE	CLC2IE	CLC1IE	78
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	—	TMR2IF	TMR1IF	79
PIR2	OSFIF	C2IF	C1IF	—	BCL1IF	NCO1IF	—	—	80
PIR3	—	—	—	—	CLC4IF	CLC3IF	CLC2IF	CLC1IF	81

Legend: — = unimplemented location, read as ‘0’. Shaded cells are not used by interrupts.

FIGURE 10-5: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES



11.8 Register Definitions: PORTC

REGISTER 11-12: PORTC: PORTC REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **RC<7:0>**: PORTC General Purpose I/O Pin bits
`1` = Port pin is ≥ V_{IH}
`0` = Port pin is ≤ V_{IL}

REGISTER 11-13: TRISC: PORTC TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **TRISC<7:0>:** PORTC Tri-State Control bits
`1` = PORTC pin configured as an input (tri-stated)
`0` = PORTC pin configured as an output

REGISTER 11-14: LATC: PORTC DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **LATC<7:0>**: PORTC Output Latch Value bits(1)

Note 1: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.

21.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

21.1 MSSP Module Overview

The Master Synchronous Serial Port (MSSPx) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSPx module can operate in one of two modes:

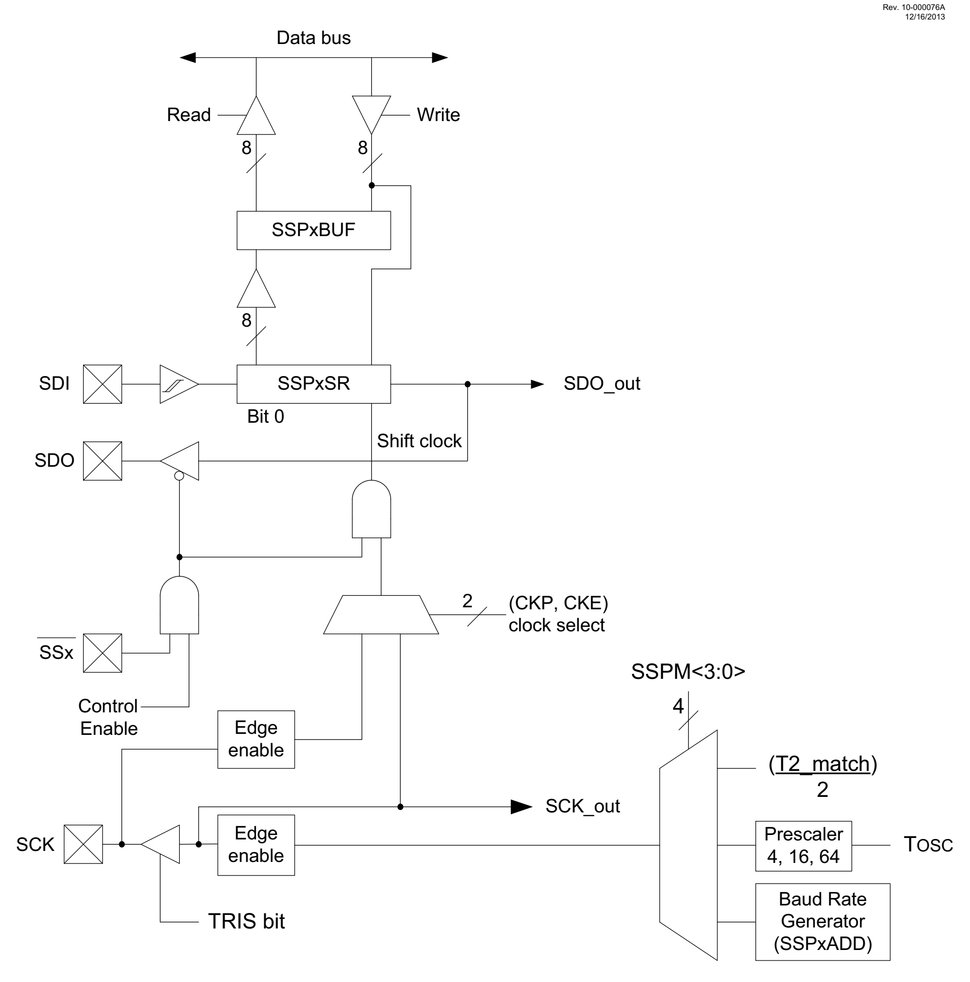
- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C™)

The SPI interface supports the following modes and features:

- Master mode
- Slave mode
- Clock Parity
- Slave Select Synchronization (Slave mode only)
- Daisy-chain connection of slave devices

Figure 21-1 is a block diagram of the SPI interface module.

FIGURE 21-1: MSSP BLOCK DIAGRAM (SPI MODE)



The I^{2}C interface supports the following modes and features:

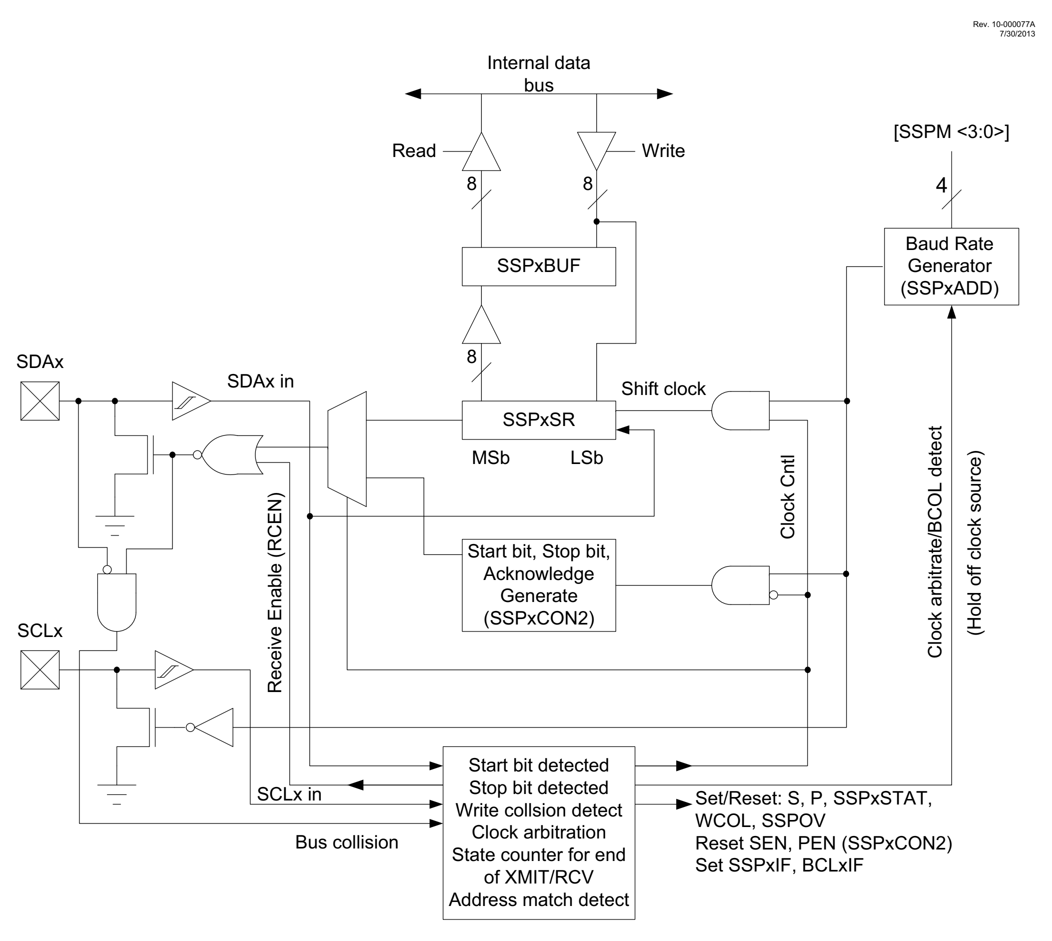
- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited Multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Address Hold and Data Hold modes
- Selectable SDAx hold times

Figure 21-2 is a block diagram of the I^{2}C interface module in Master mode. Figure 21-3 is a diagram of the I^{2}C interface module in Slave mode.

Note 1: In devices with more than one MSSP module, it is very important to pay close attention to SSPxCONx register names. SSPxCON1 and SSPxCON2 registers control different operational aspects of the same module, while SSPxCON1 and SSP2CON1 control the same features for two different modules.

2: Throughout this section, generic references to an MSSPx module in any of its operating modes may be interpreted as being equally applicable to MSSPx or MSSP2. Register names, module I/O signals, and bit names may use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module when required.

FIGURE 21-2: MSSPX BLOCK DIAGRAM (I^{2}C™ MASTER MODE)



21.2 SPI Mode Overview

The Serial Peripheral Interface (SPI) bus is a synchronous serial data communication bus that operates in Full-Duplex mode. Devices communicate in a master/slave environment where the master device initiates the communication. A slave device is controlled through a Chip Select known as Slave Select.

The SPI bus specifies four signal connections:

- Serial Clock (SCKx)
- Serial Data Out (SDOx)
- Serial Data In (SDIx)
- Slave Select ($\overline{\text{SSx}}$)

Figure 21-1 shows the block diagram of the MSSP module when operating in SPI mode.

The SPI bus operates with a single master device and one or more slave devices. When multiple slave devices are used, an independent Slave Select connection is required from the master device to each slave device.

Figure 21-4 shows a typical connection between a master device and multiple slave devices.

The master selects only one slave at a time. Most slave devices have tri-state outputs so their output signal appears disconnected from the bus when they are not selected.

Transmissions involve two shift registers, eight bits in size, one in the master and one in the slave. With either the master or the slave device, data is always shifted out one bit at a time, with the Most Significant bit (MSb) shifted out first. At the same time, a new Least Significant bit (LSb) is shifted into the same register.

Figure 21-5 shows a typical connection between two processors configured as master and slave devices.

Data is shifted out of both shift registers on the programmed clock edge and latched on the opposite edge of the clock.

The master device transmits information out on its SDOx output pin which is connected to, and received by, the slave's SDIx input pin. The slave device transmits information out on its SDOx output pin, which is connected to, and received by, the master's SDIx input pin.

To begin communication, the master device first sends out the clock signal. Both the master and the slave devices should be configured for the same clock polarity.

The master device starts a transmission by sending out the MSb from its shift register. The slave device reads this bit from that same line and saves it into the LSb position of its shift register.

During each SPI clock cycle, a full-duplex data transmission occurs. This means that while the master device is sending out the MSb from its shift register (on its SDOx pin) and the slave device is reading this bit and saving it as the LSb of its shift register, that the slave device is also sending out the MSb from its shift register (on its SDOx pin) and the master device is reading this bit and saving it as the LSb of its shift register.

After eight bits have been shifted out, the master and slave have exchanged register values.

If there is more data to exchange, the shift registers are loaded with new data and the process repeats itself.

Whether the data is meaningful or not (dummy data), depends on the application software. This leads to three scenarios for data transmission:

- Master sends useful data and slave sends dummy data.
- Master sends useful data and slave sends useful data.
- Master sends dummy data and slave sends useful data.

Transmissions may involve any number of clock cycles. When there is no more data to be transmitted, the master stops sending the clock signal and it deselects the slave.

Every slave device connected to the bus that has not been selected through its slave select line must disregard the clock and transmission signals and must not transmit out any data of its own.

FIGURE 21-32: BUS COLLISION TIMING FOR TRANSMIT AND ACKNOWLEDGE

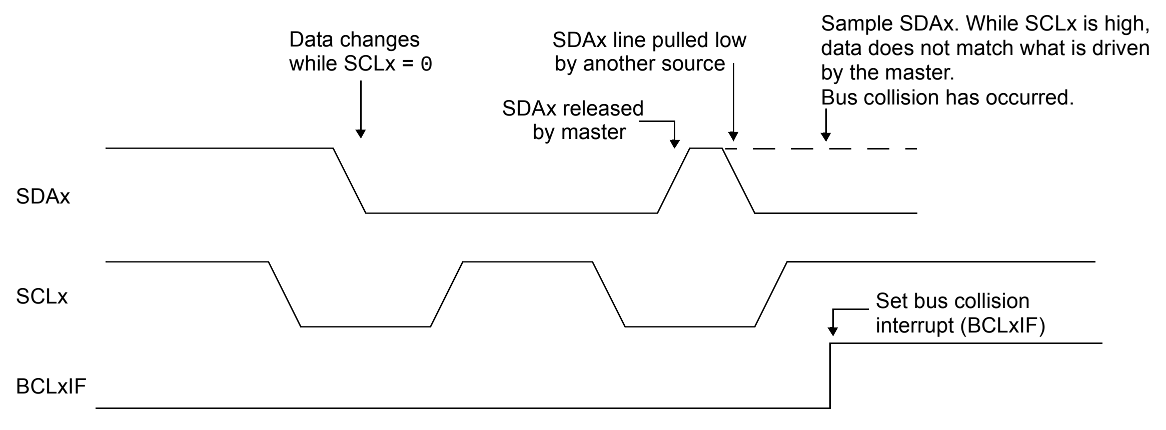


FIGURE 21-34: BUS COLLISION DURING START CONDITION (SCLX = 0)

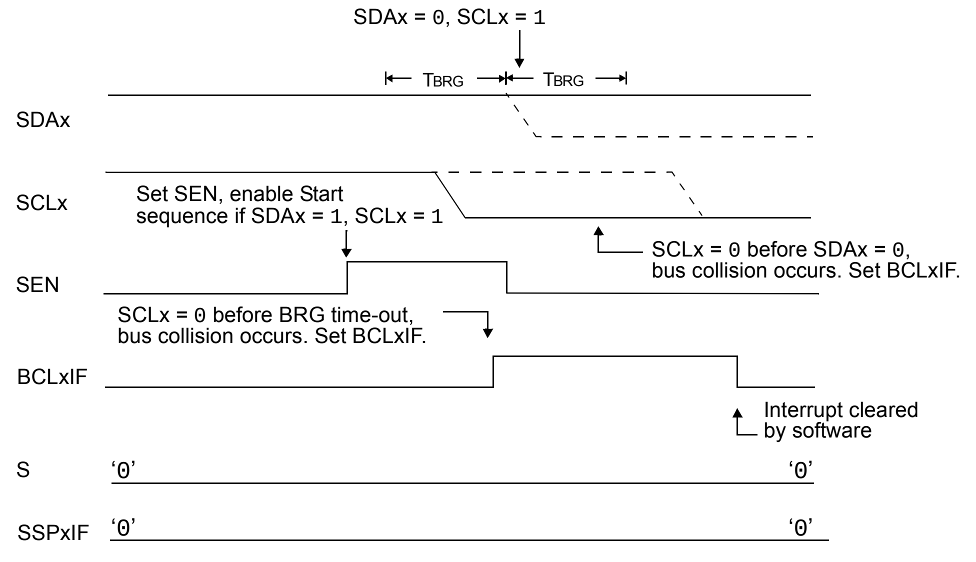


FIGURE 21-35: BRG RESET DUE TO SDA ARBITRATION DURING START CONDITION

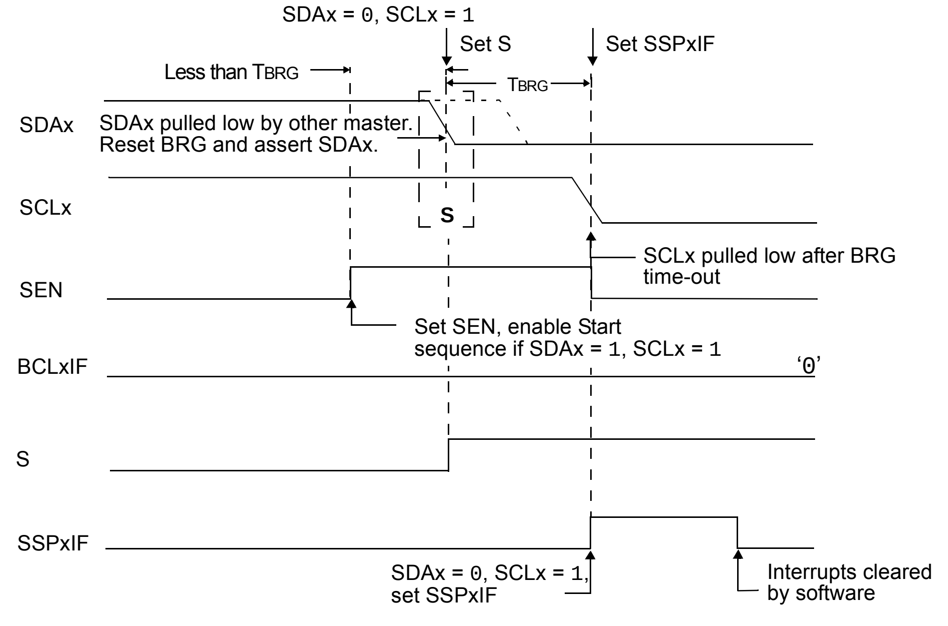


TABLE 22-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 16.000 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	13332	300.0	0.00	9215
1200	1200	-0.01	4166	1200	0.00	3839	1200.1	0.01	3332	1200	0.00	2303
2400	2400	0.02	2082	2400	0.00	1919	2399.5	-0.02	1666	2400	0.00	1151
9600	9597	-0.03	520	9600	0.00	479	9592	-0.08	416	9600	0.00	287
10417	10417	0.00	479	10425	0.08	441	10417	0.00	383	10433	0.16	264
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.23k	0.16	207	19.20k	0.00	143
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.97k	0.64	68	57.60k	0.00	47
115.2k	116.3k	0.94	42	115.2k	0.00	39	114.29k	-0.79	34	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 8.000 MHz			FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

23.0 PULSE-WIDTH MODULATION (PWM) MODULE

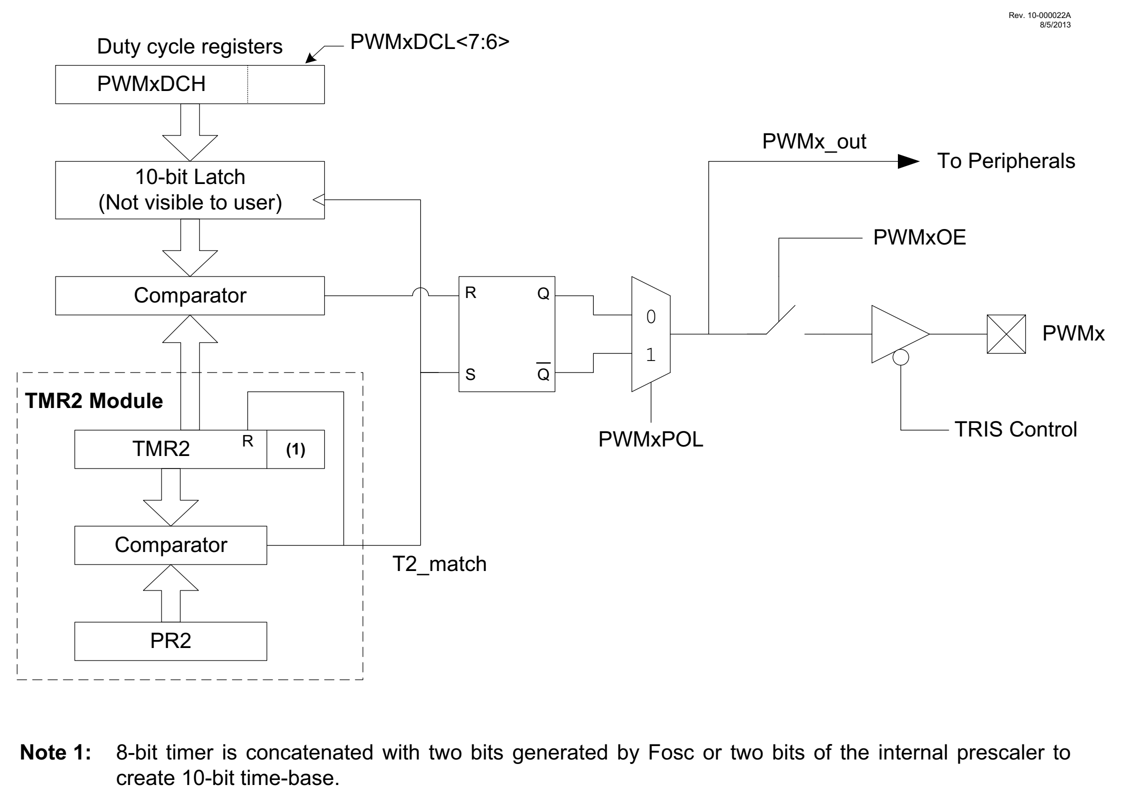
The PWM module generates a Pulse-Width Modulated signal determined by the duty cycle, period, and resolution that are configured by the following registers:

- PR2
- T2CON
- PWMxDCH
- PWMxDCL
- PWMxCON

Figure 23-1 shows a simplified block diagram of PWM operation.

For a step-by-step procedure on how to set up this module for PWM operation, refer to **Section 23.1.9 "Setup for PWM Operation using PWMx Pins"**.

FIGURE 23-1: SIMPLIFIED PWM BLOCK DIAGRAM



Note 1: 8-bit timer is concatenated with two bits generated by Fosc or two bits of the internal prescaler to create 10-bit time-base.

FIGURE 30-49: V_{OH} vs. I_{OH} OVER TEMPERATURE, V_{DD} = 3.0V

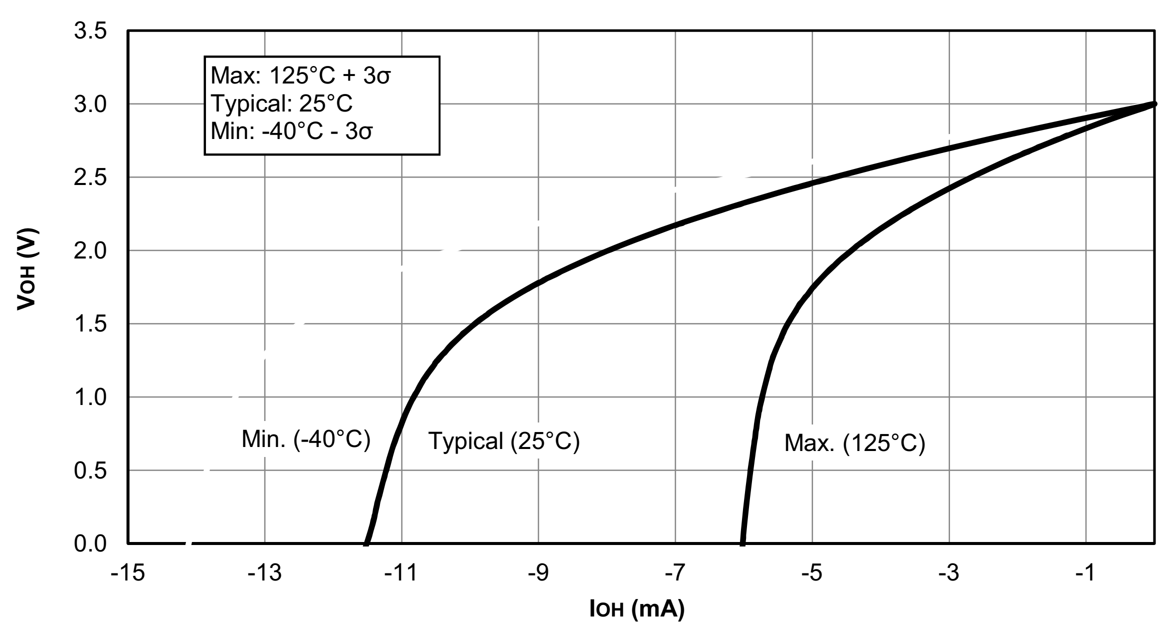


FIGURE 30-50: V_{OL} vs. I_{OL} OVER TEMPERATURE, V_{DD} = 3.0V

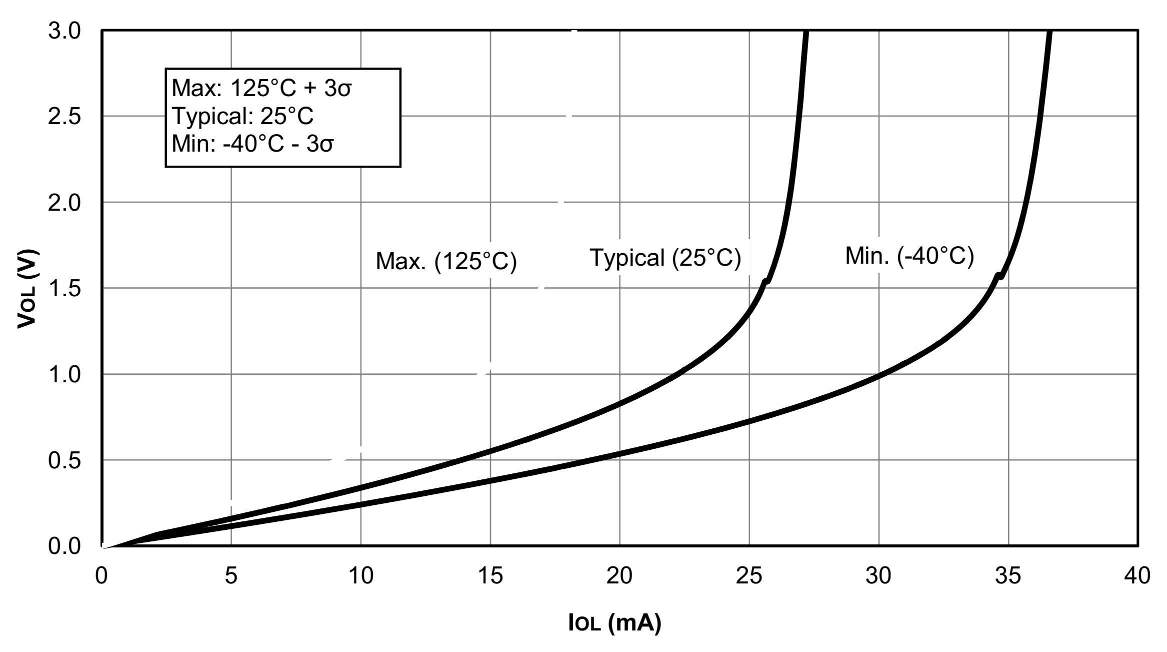


FIGURE 30-59: BROWN-OUT RESET VOLTAGE, BORV = `0`

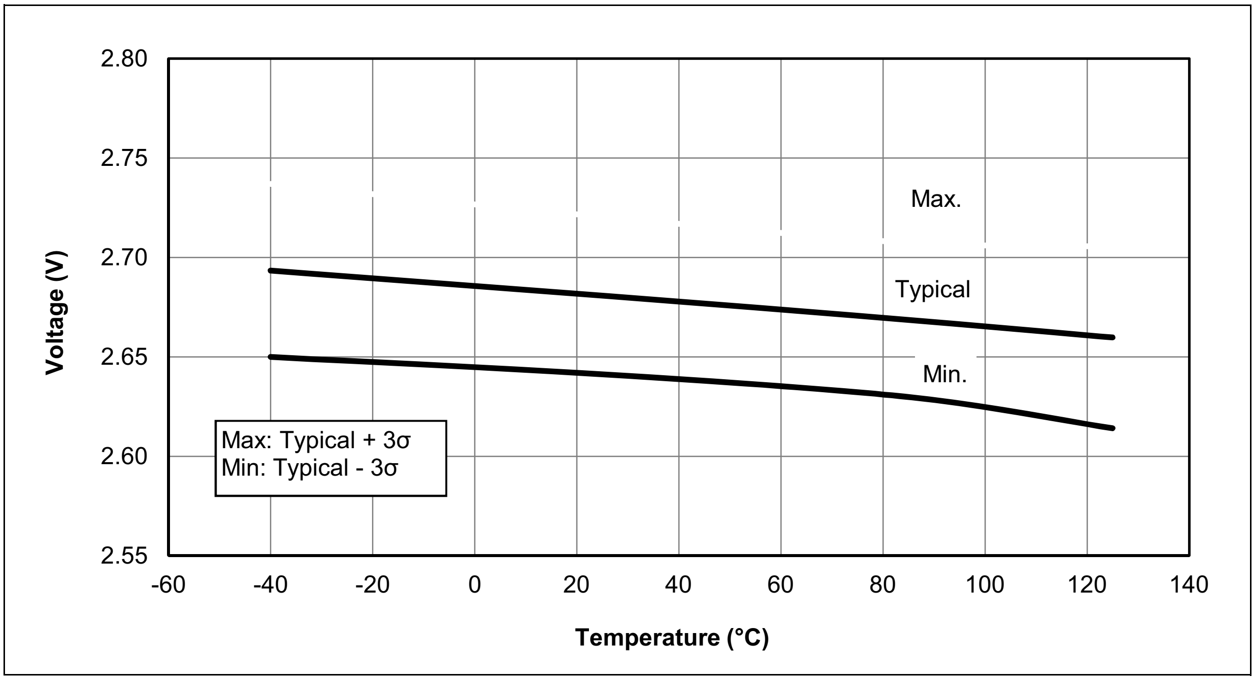


FIGURE 30-62: WDT TIME-OUT PERIOD

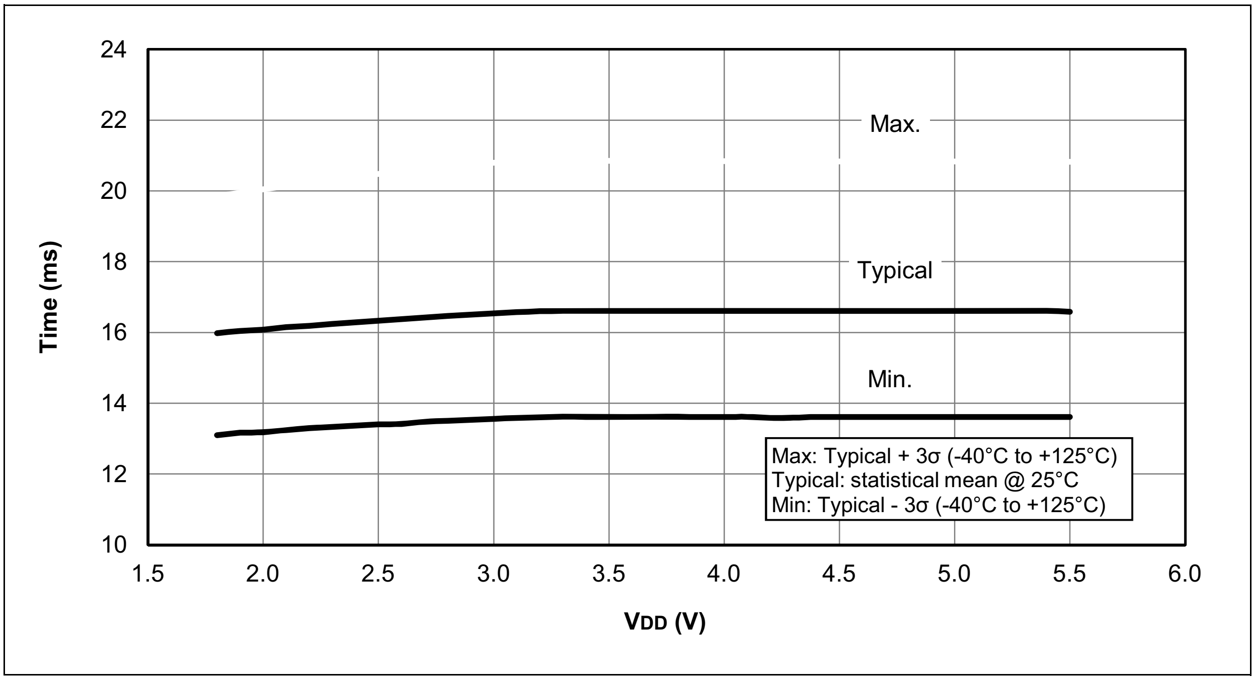
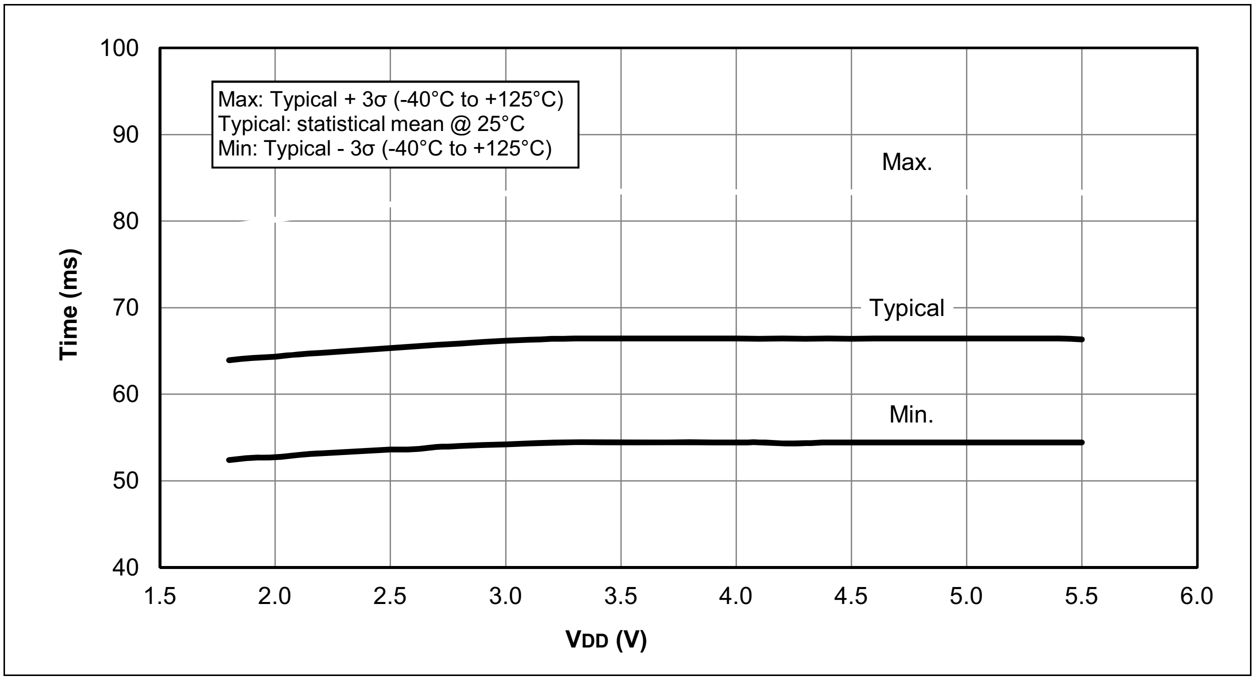


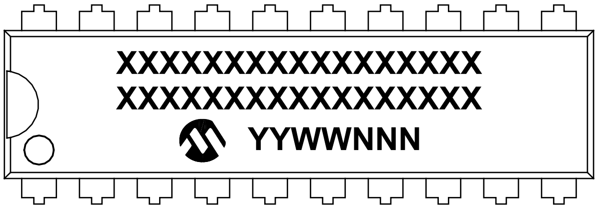
FIGURE 30-63: PWRT PERIOD



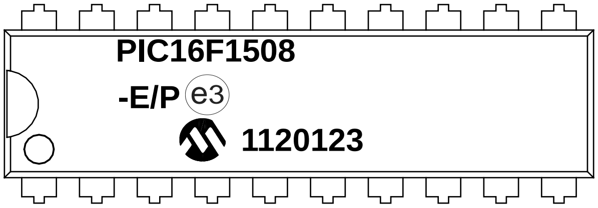
32.0 PACKAGING INFORMATION

32.1 Package Marking Information

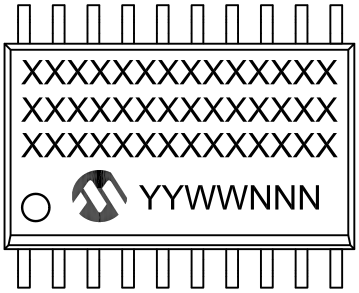
20-Lead PDIP (300 mil)



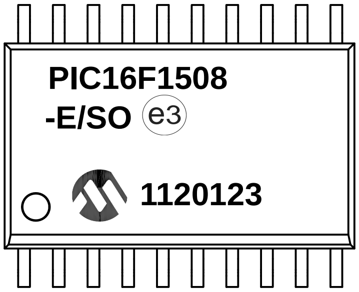
Example



20-Lead SOIC (7.50 mm)



Example



Legend:		
	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

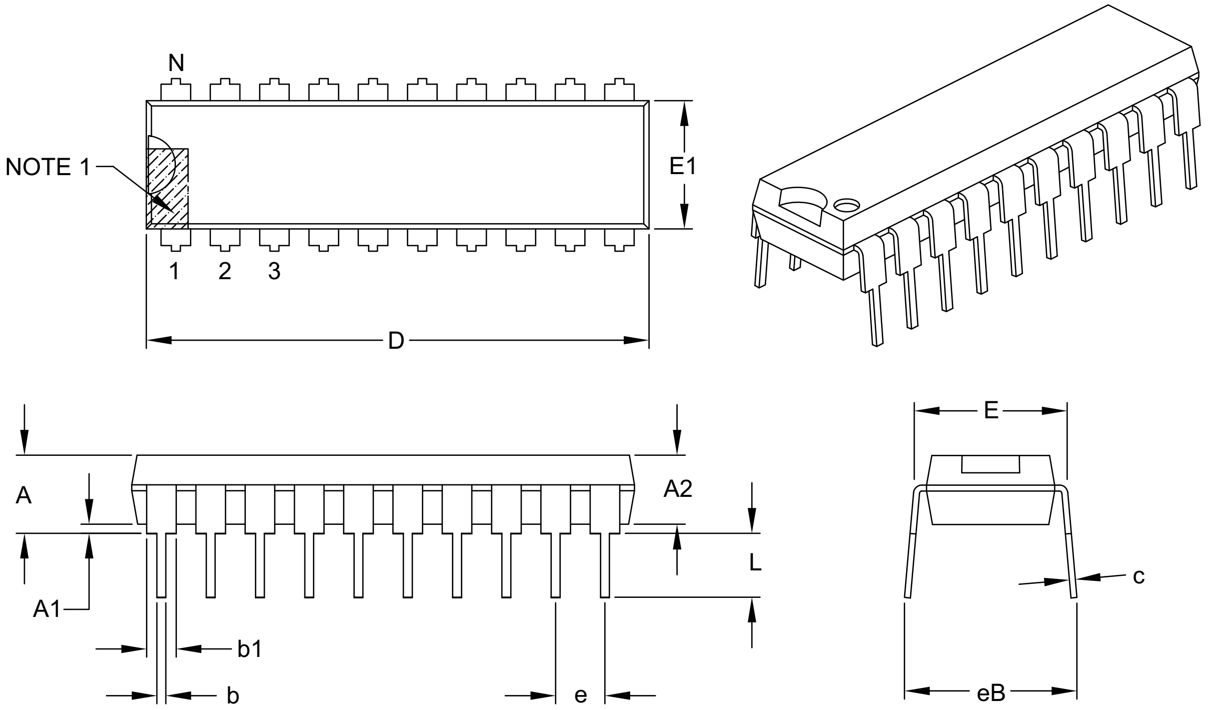
* Standard PICmicro® device marking consists of Microchip part number, year code, week code and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

32.2 Package Details

The following sections give the technical details of the packages.

20-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.980	1.030	1.060
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-019B